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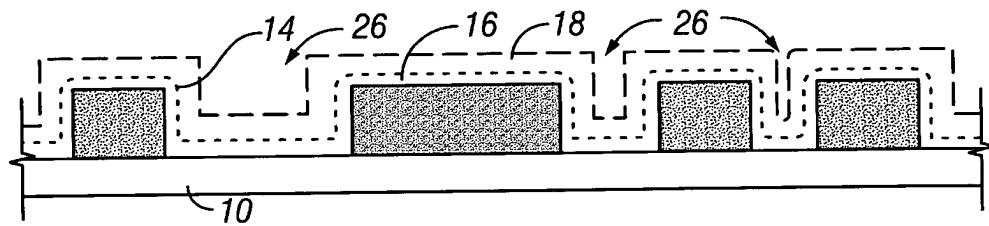


FIG. 1

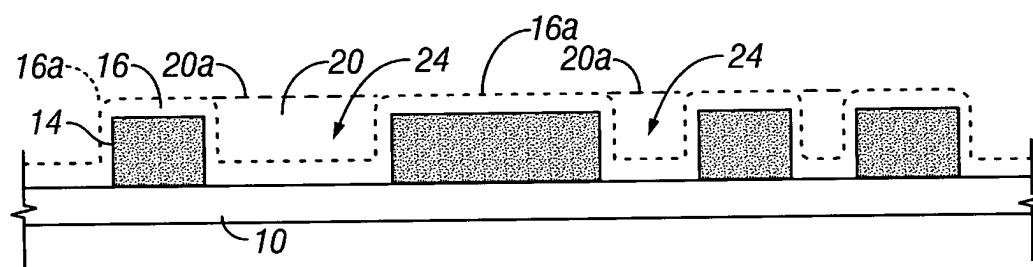


FIG. 2A

Figure : After deposition of gapfilling polymer and CMP

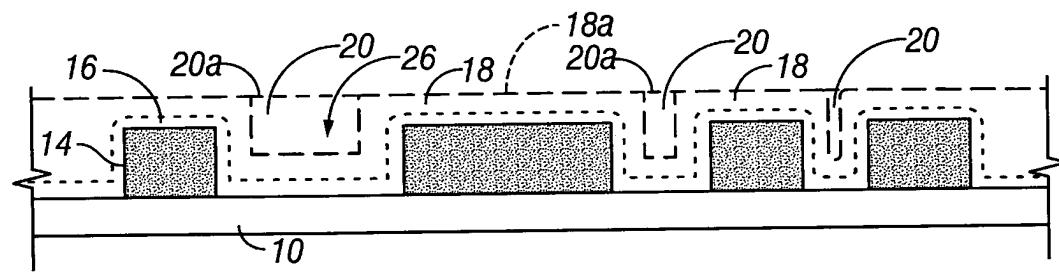


FIG. 2B



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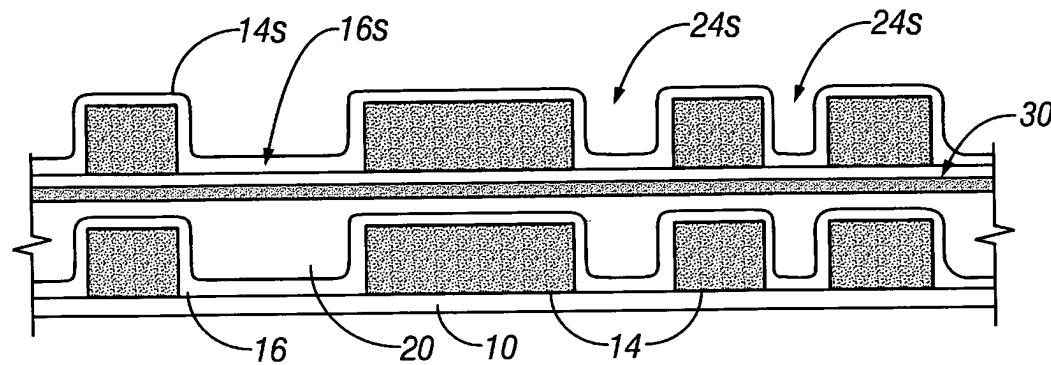


FIG. 3

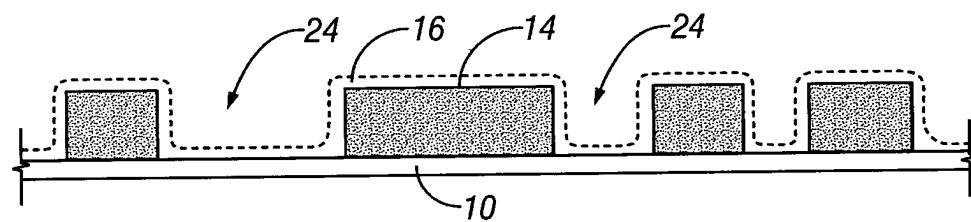


FIG. 4

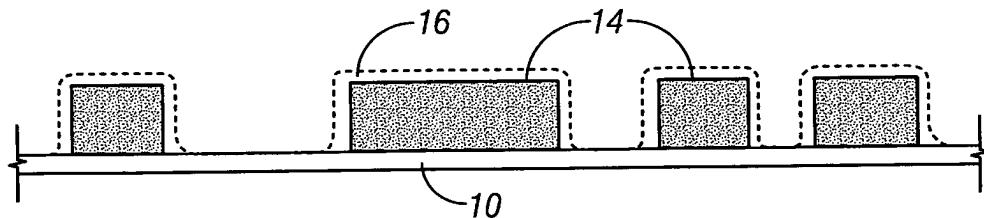


FIG. 5



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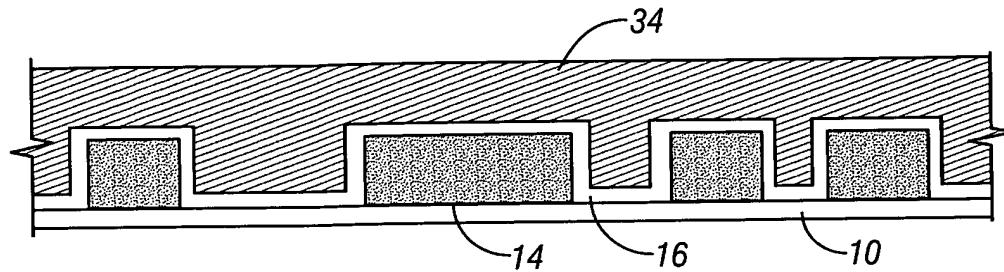


FIG. 6

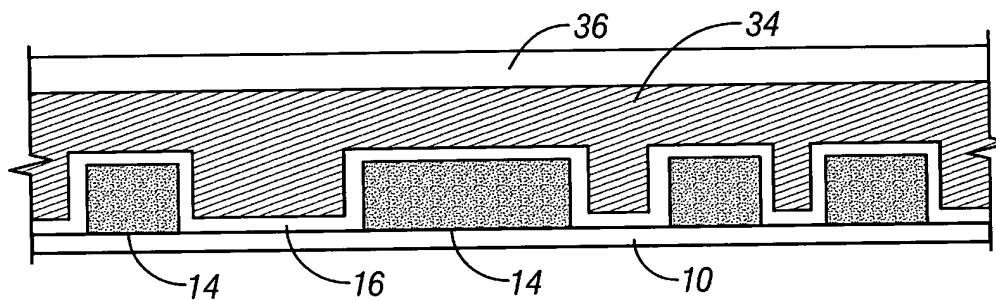


FIG. 7

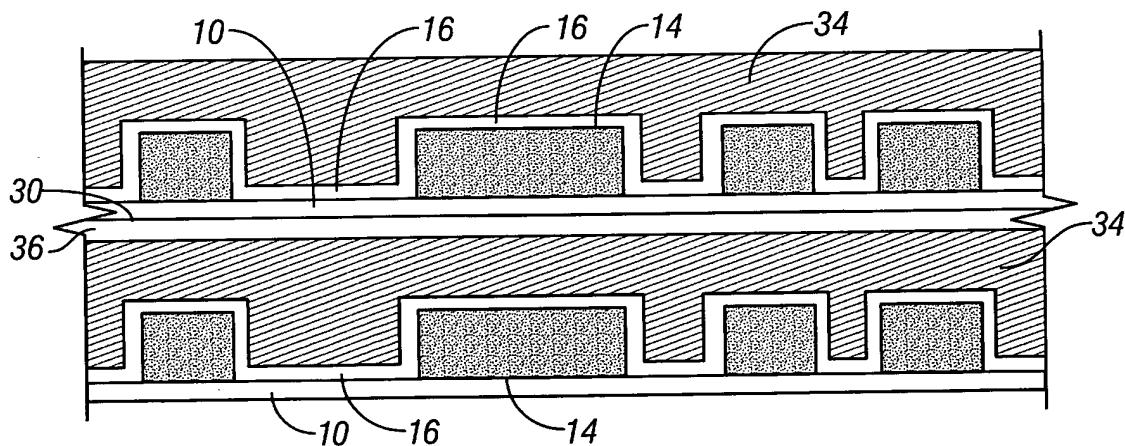


FIG. 8



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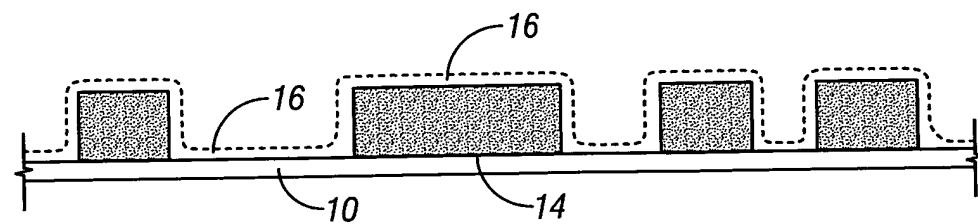


FIG. 9

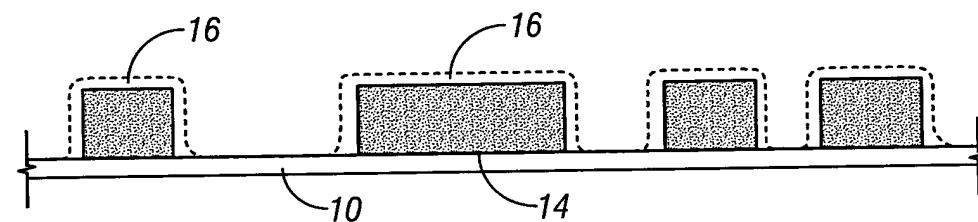


FIG. 10

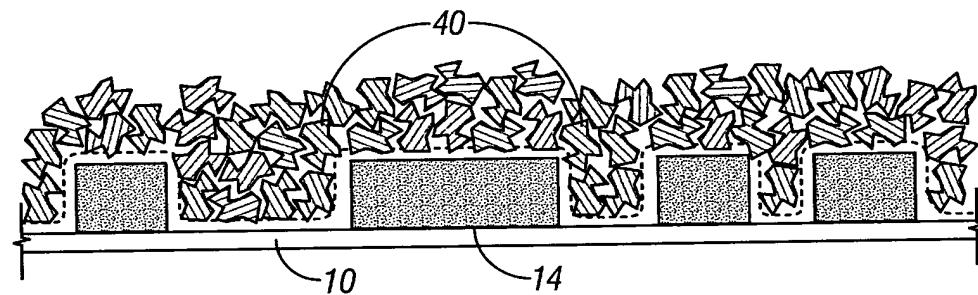


FIG. 11

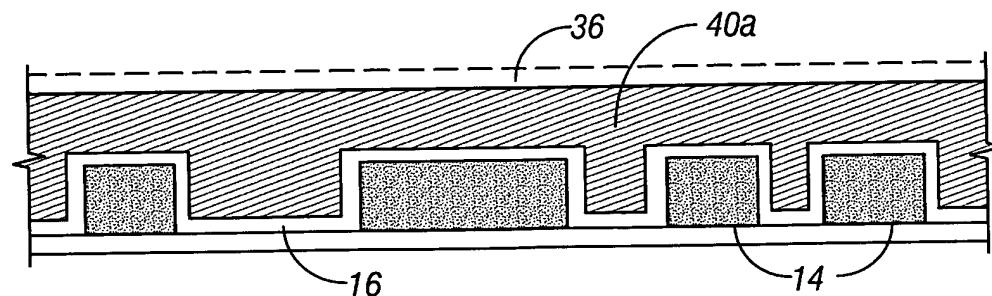


FIG. 12



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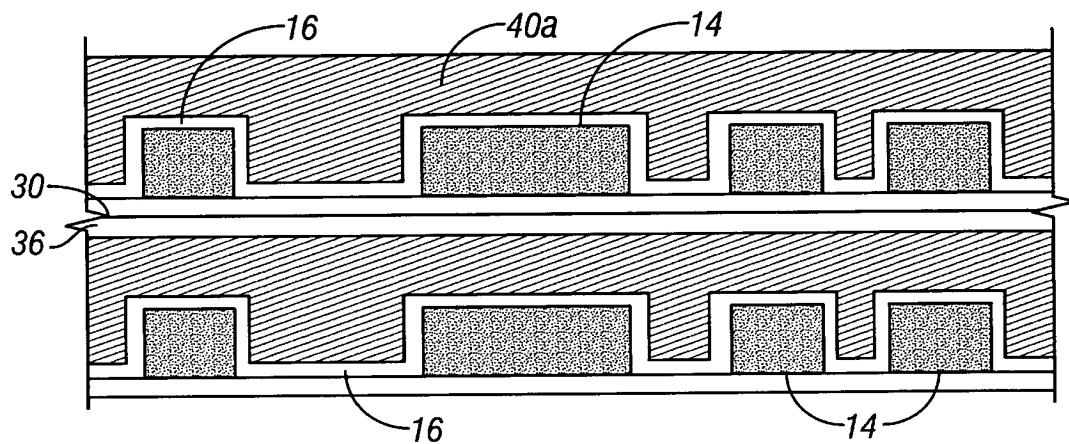


FIG. 13

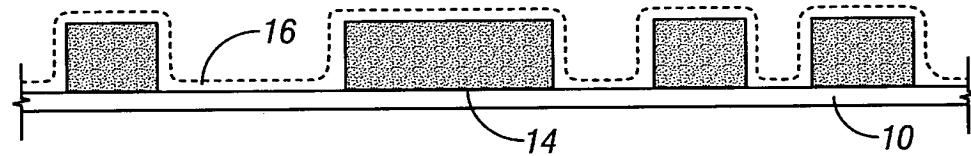


FIG. 14

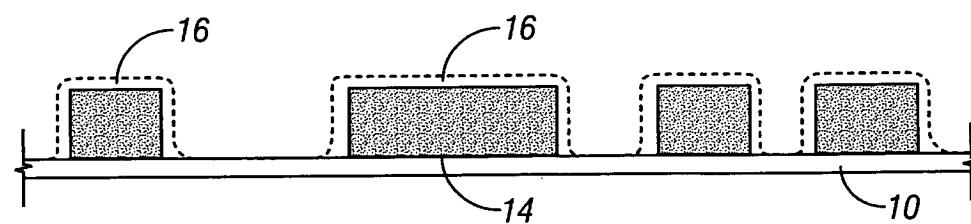


FIG. 15



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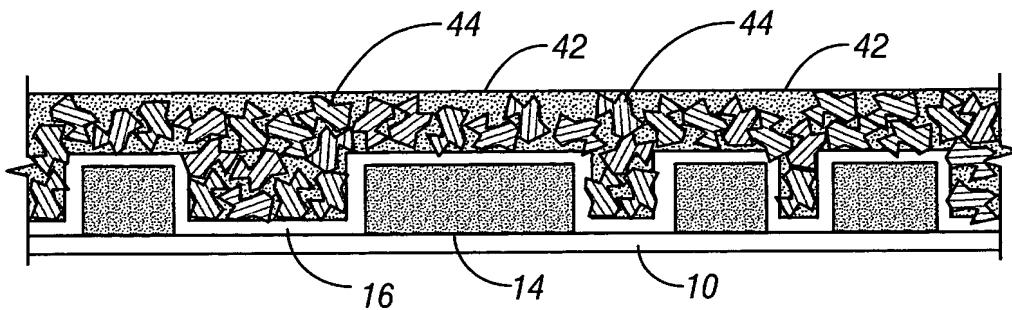


FIG. 16

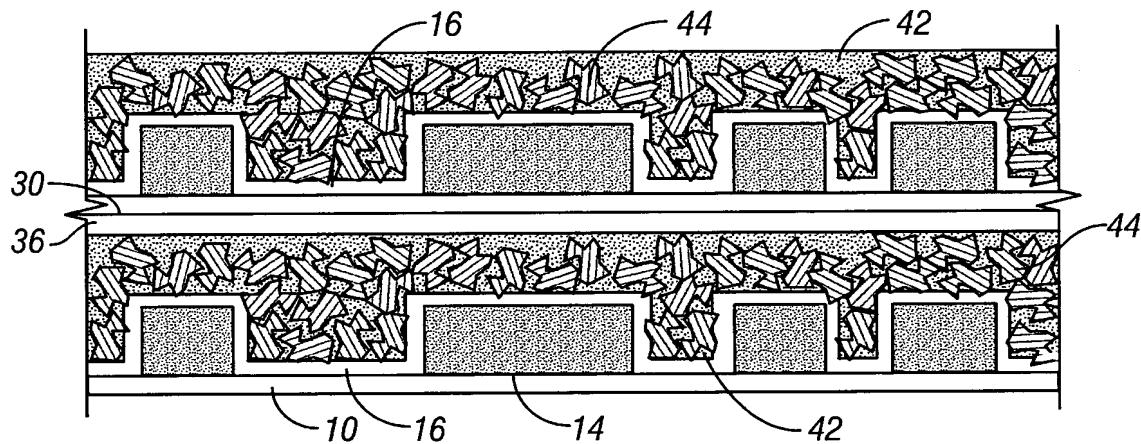
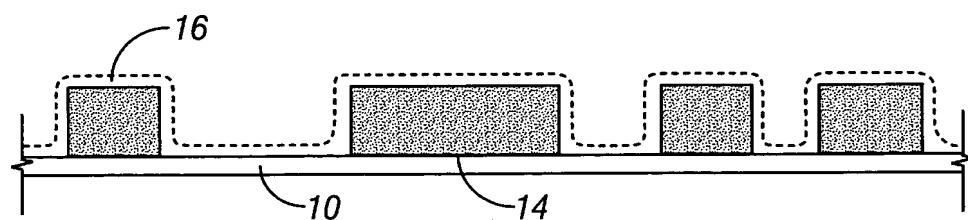


FIG. 17



b) or Masking can be used to make polymer layer discontinuous from conductor to conductor.

FIG. 18



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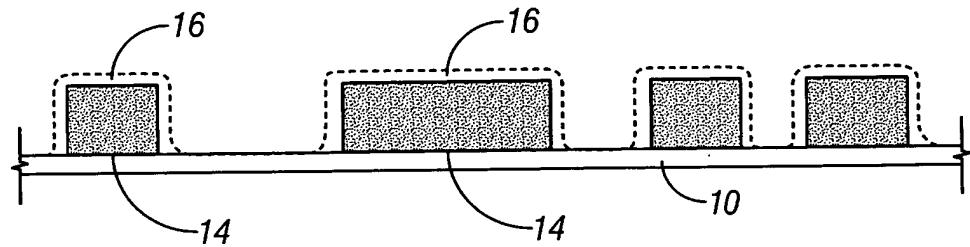


FIG. 19

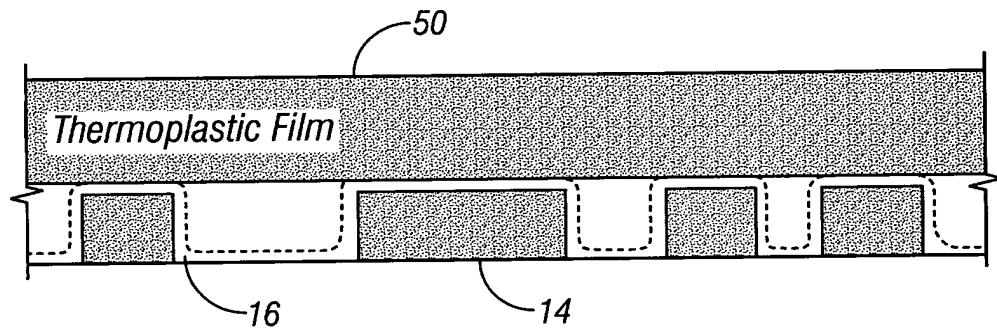


FIG. 20

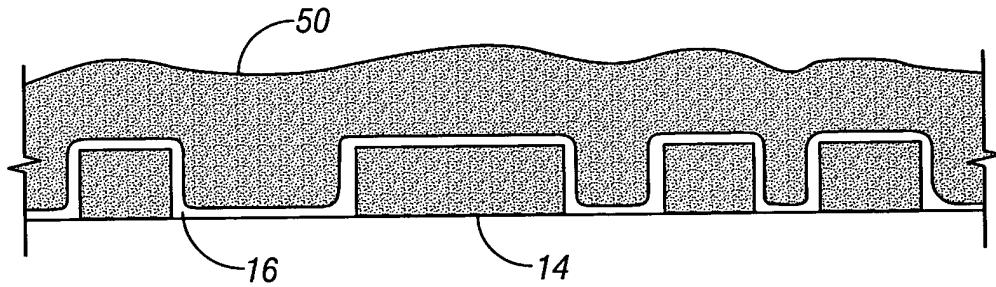


FIG. 21



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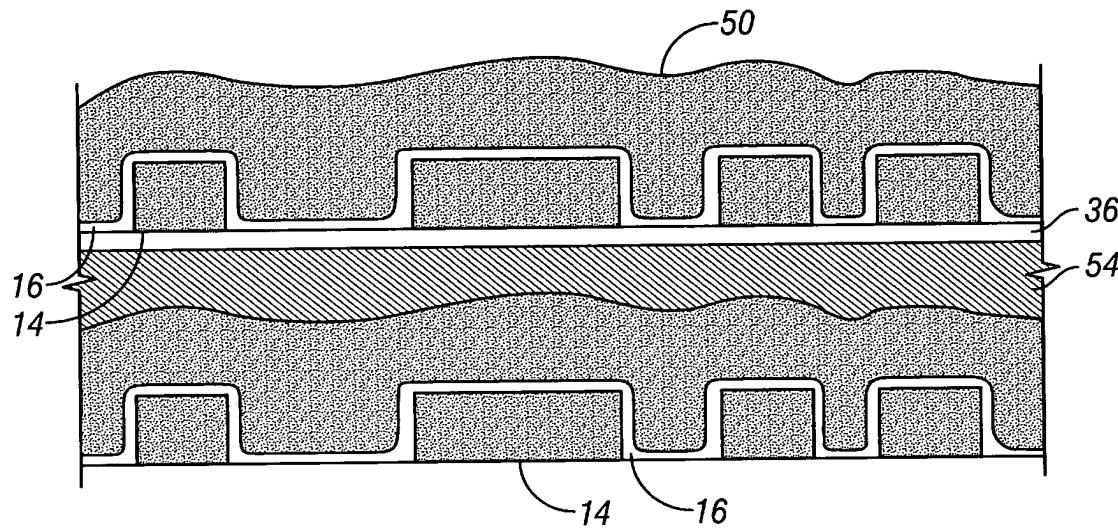


FIG. 22

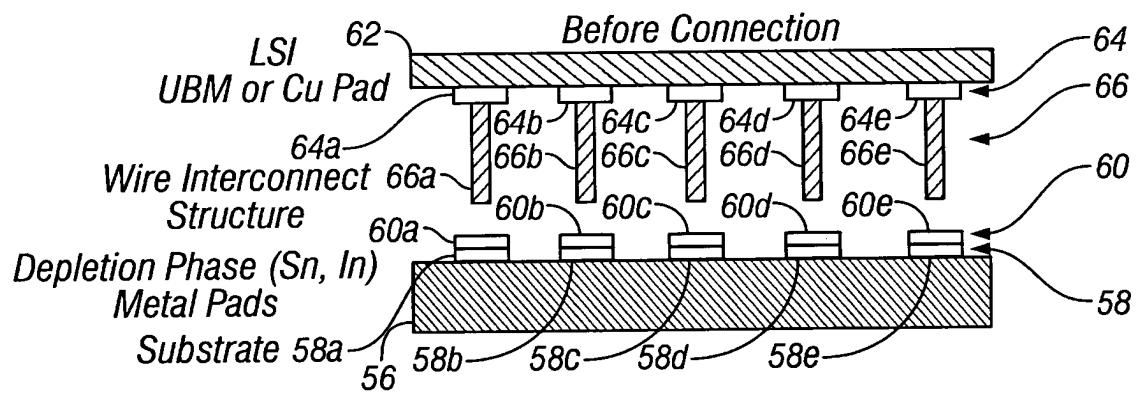


FIG. 23



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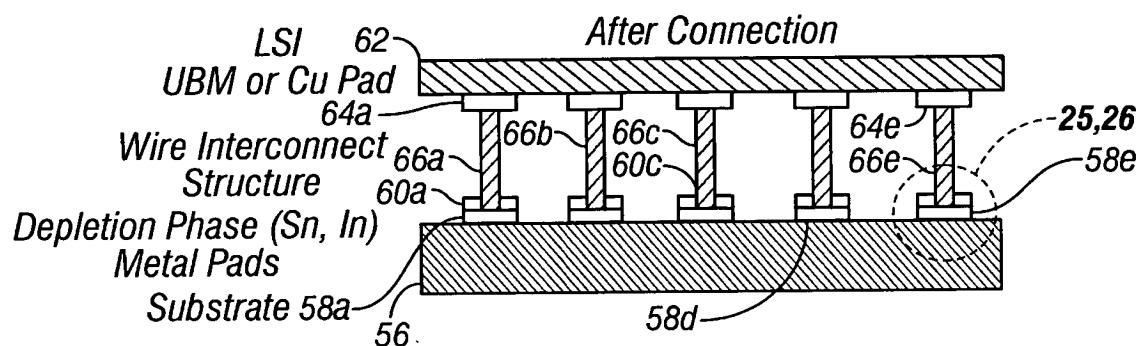


FIG. 24

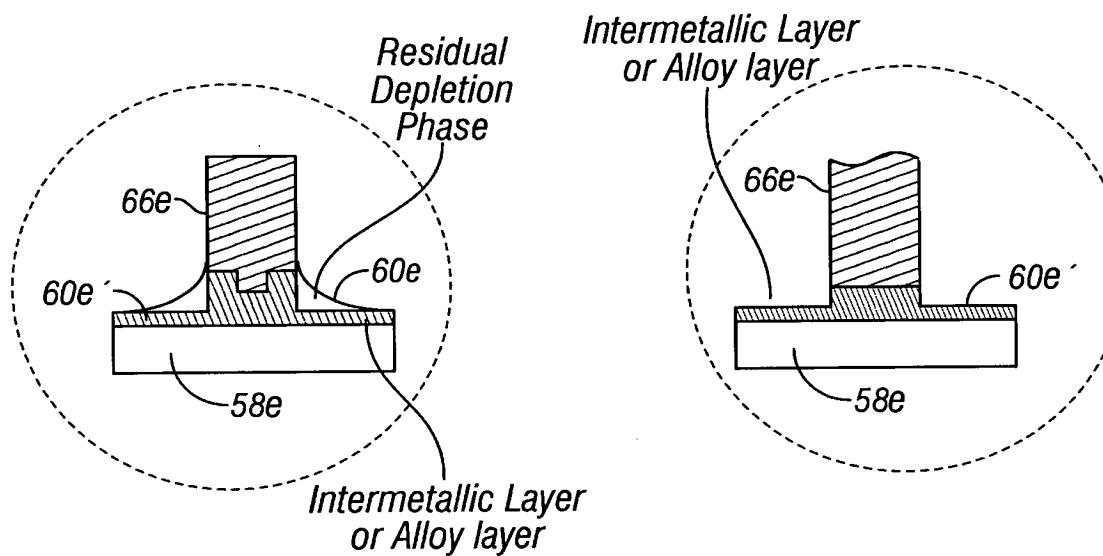


FIG. 25

FIG. 26



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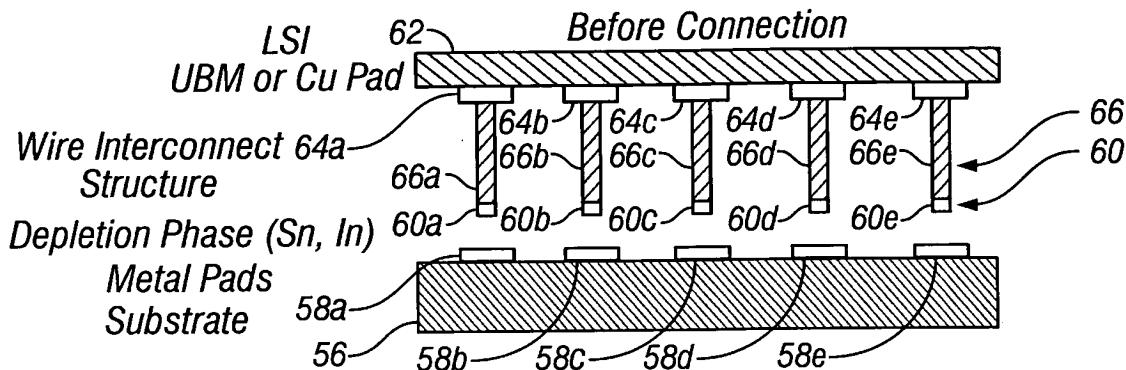


FIG. 27

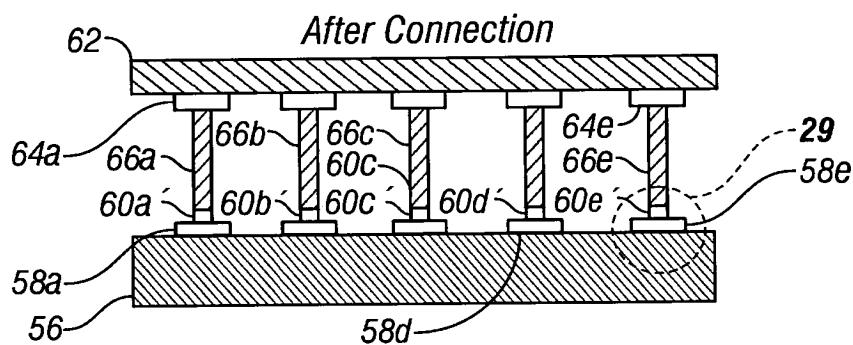


FIG. 28

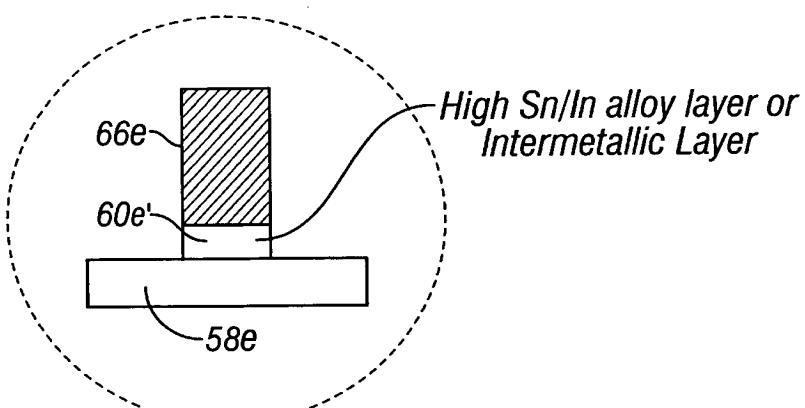


FIG. 29



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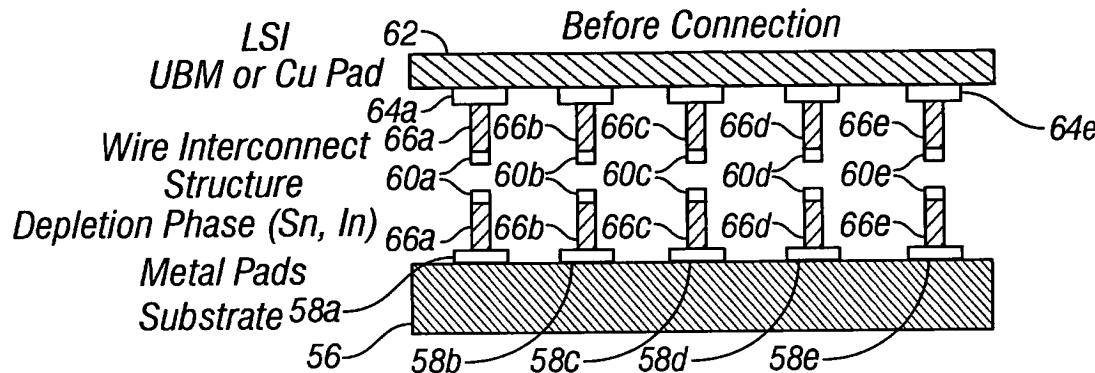


FIG. 30

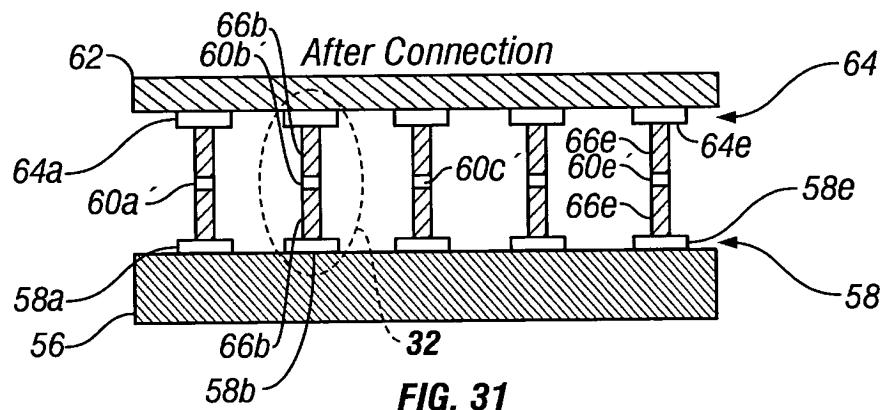


FIG. 31

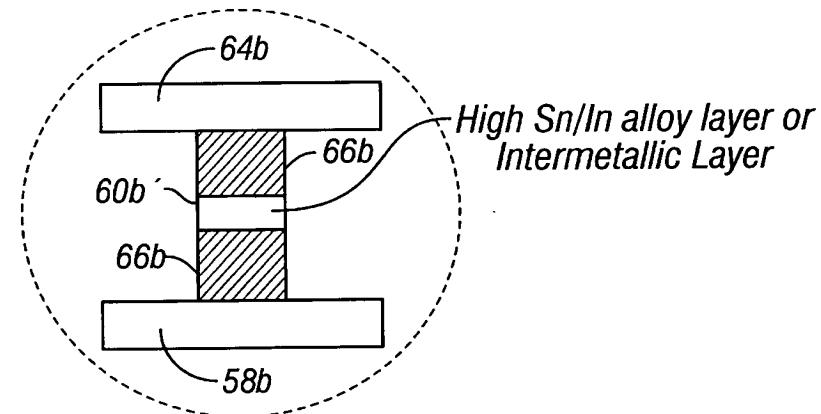


FIG. 32



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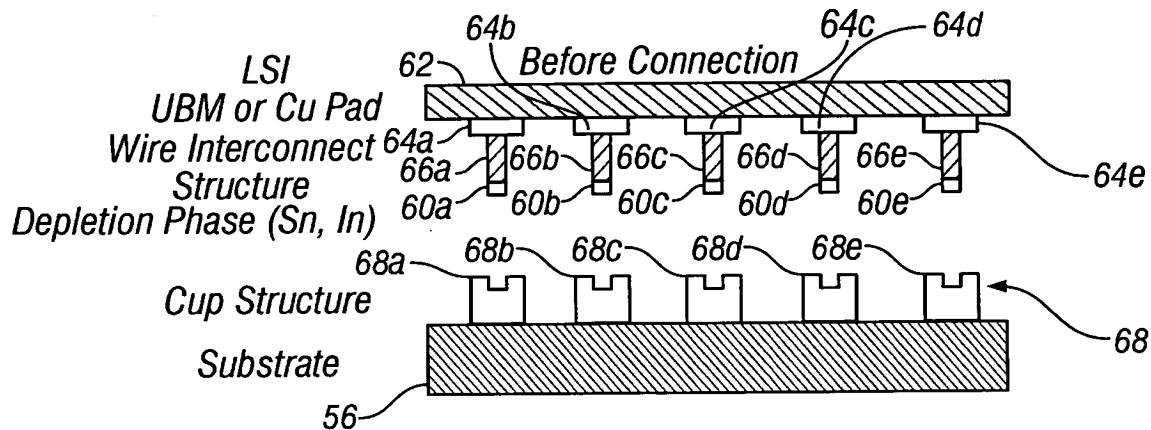


FIG. 33

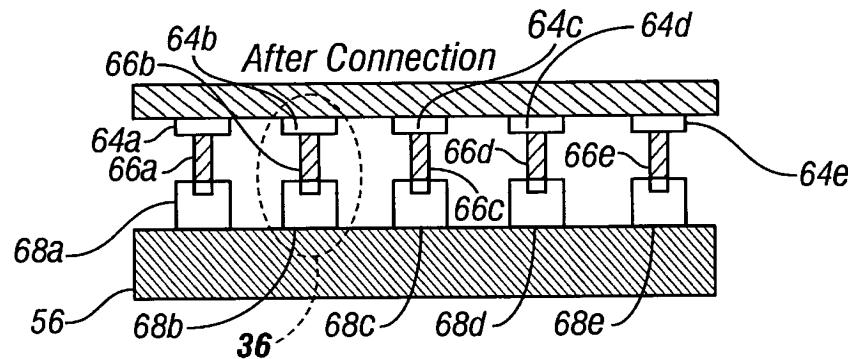
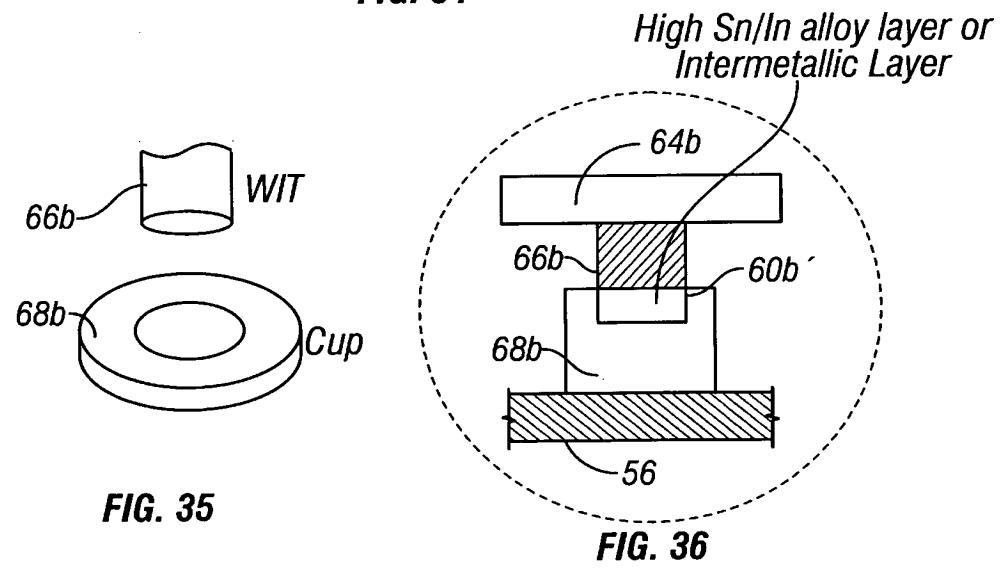
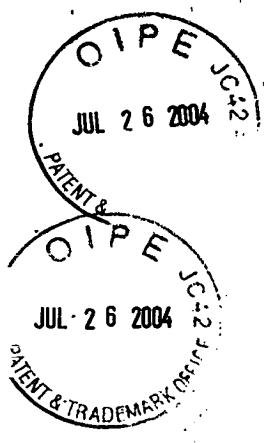


FIG. 34





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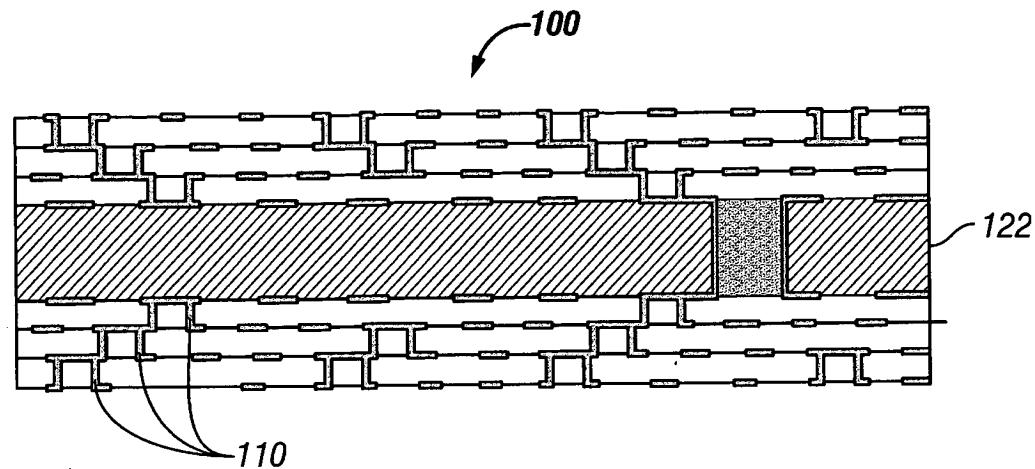


FIG. 37

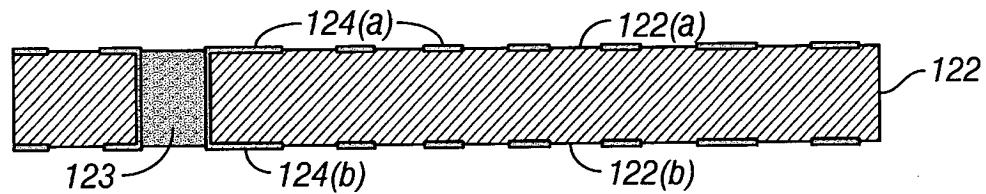


FIG. 38

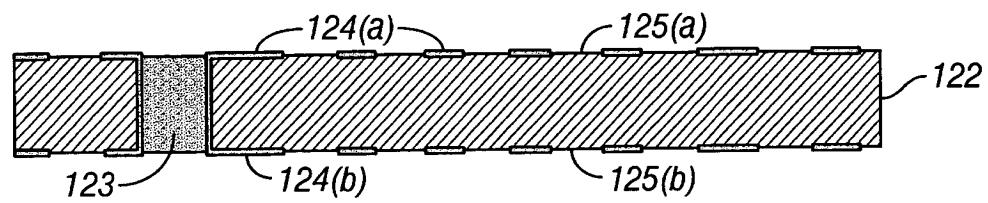


FIG. 39



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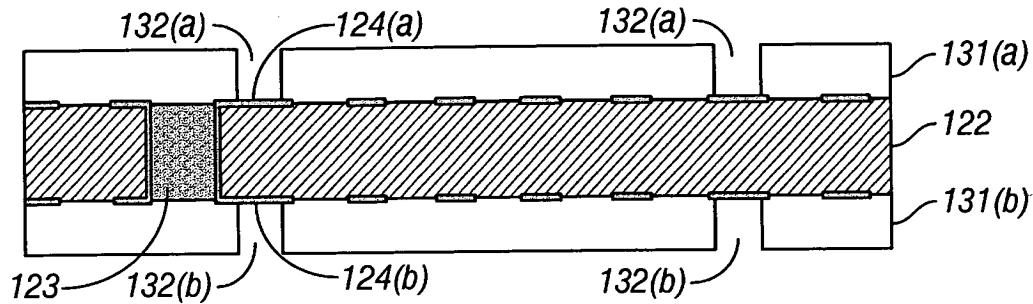


FIG. 40

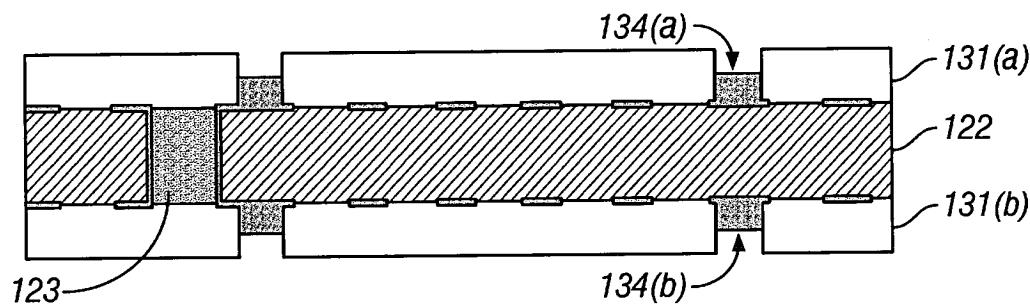


FIG. 41

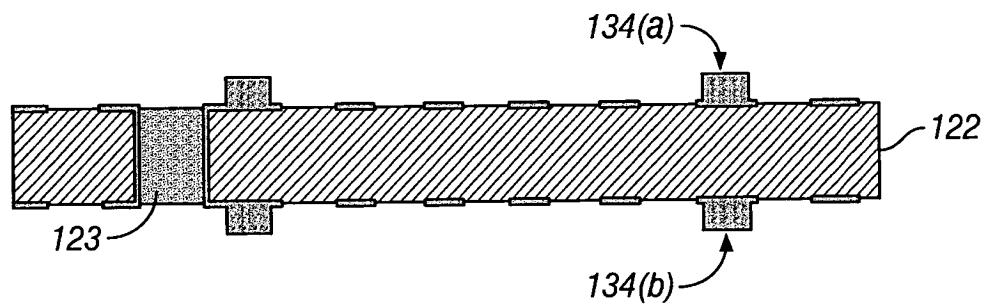


FIG. 42



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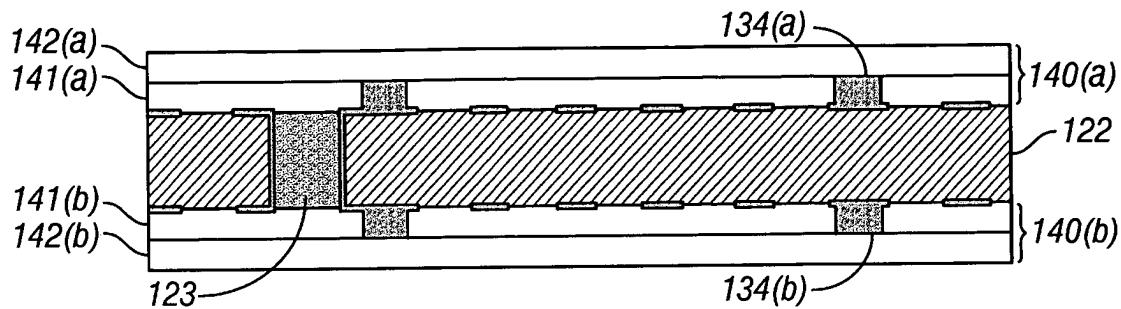


FIG. 43

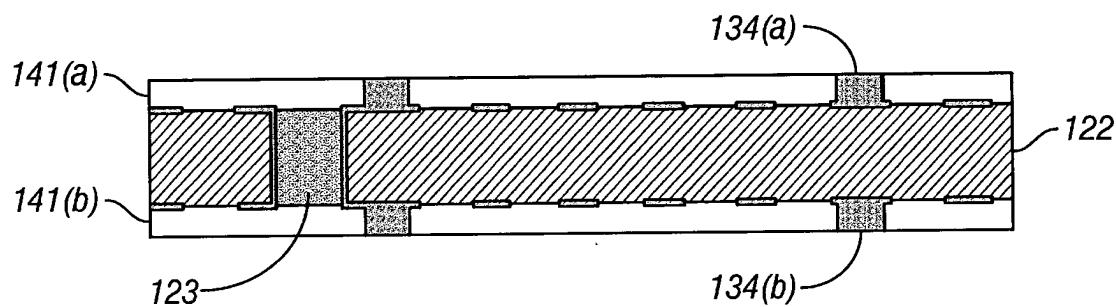


FIG. 44

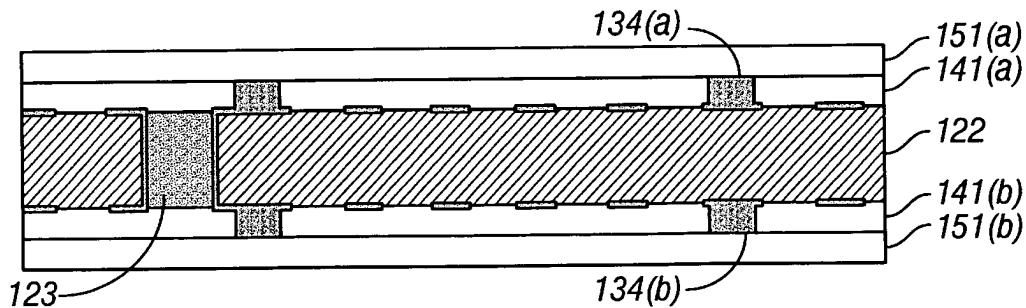


FIG. 45



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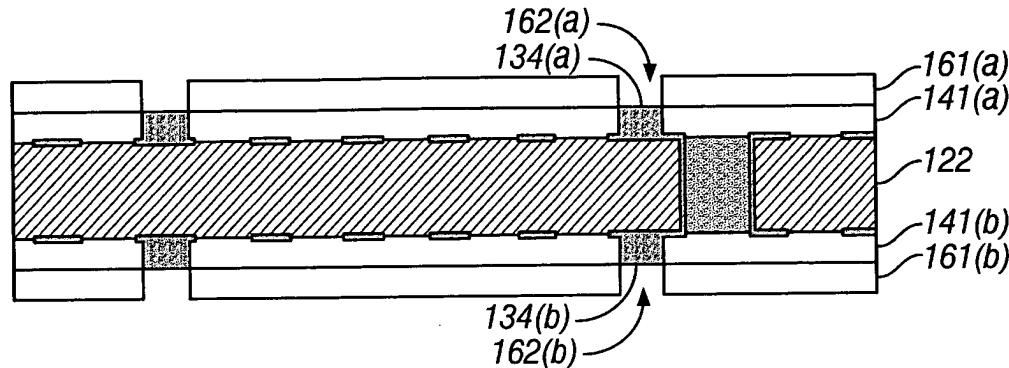


FIG. 46

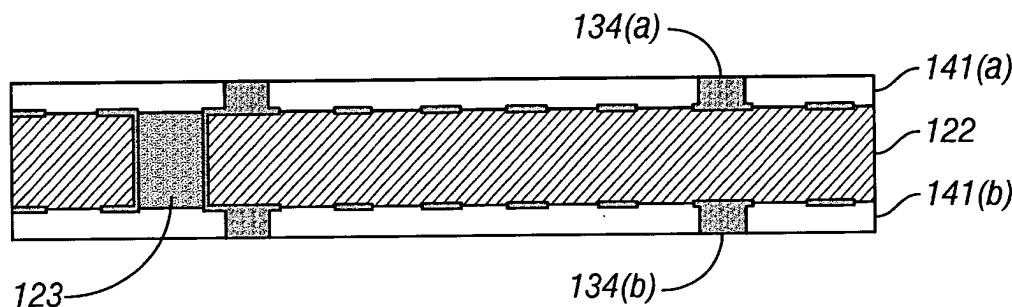


FIG. 47

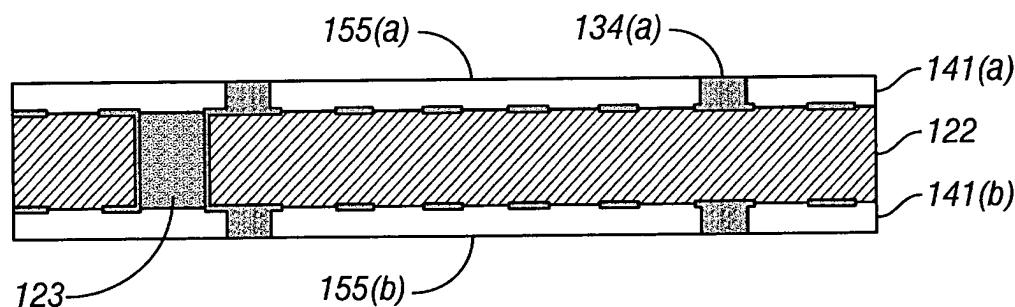


FIG. 48



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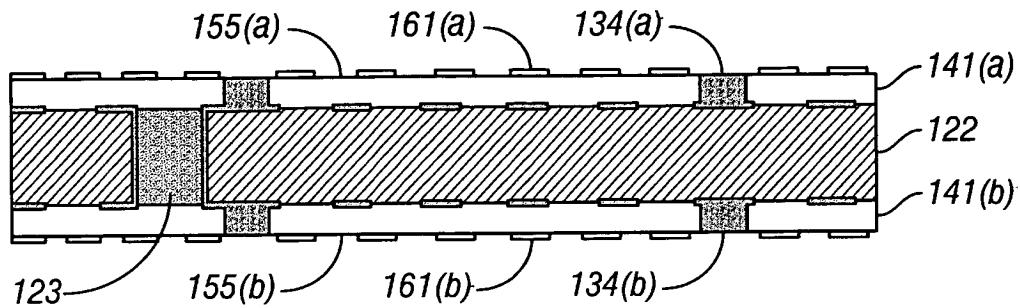


FIG. 49

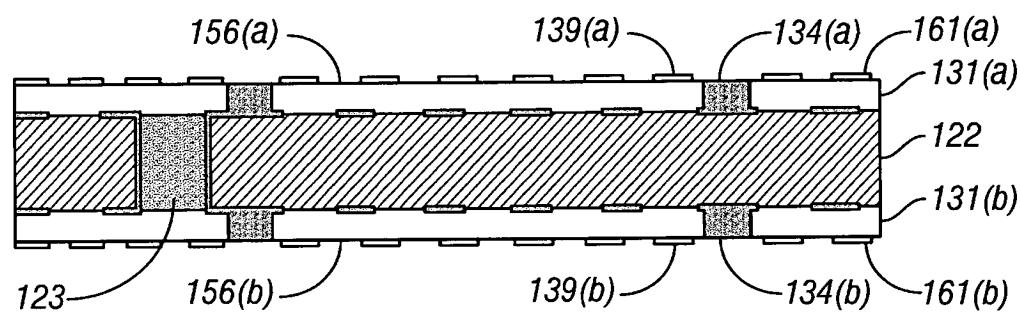


FIG. 50

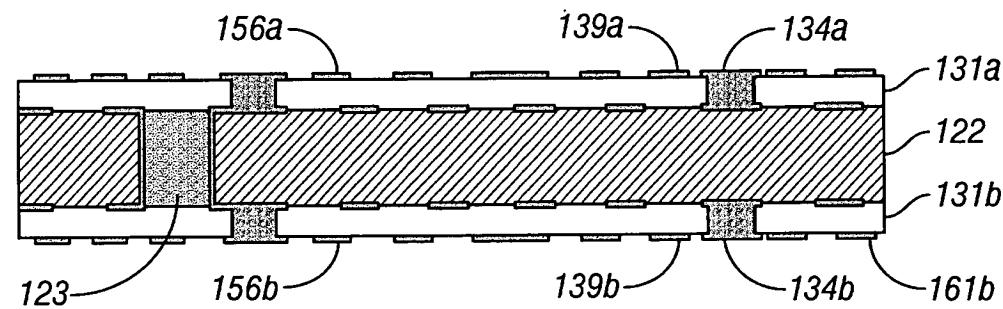


FIG. 51



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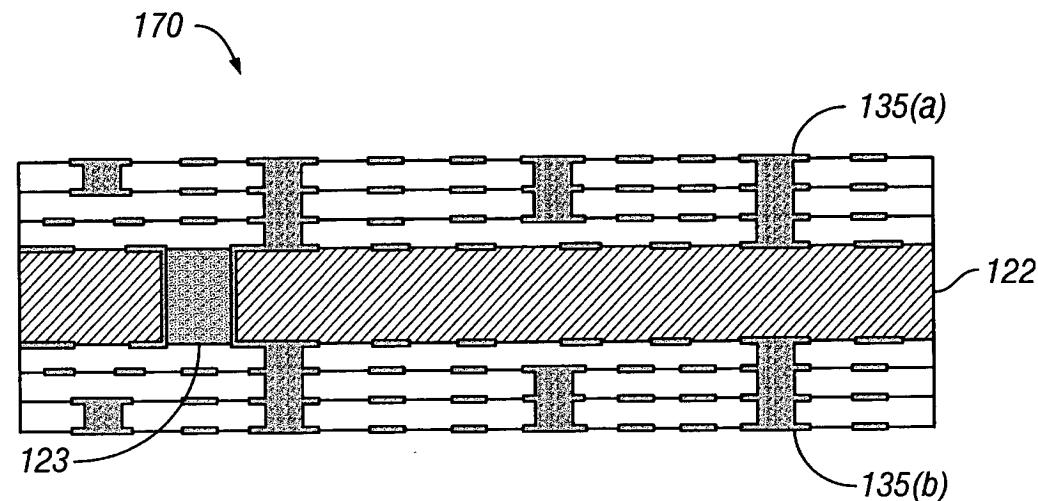


FIG. 52

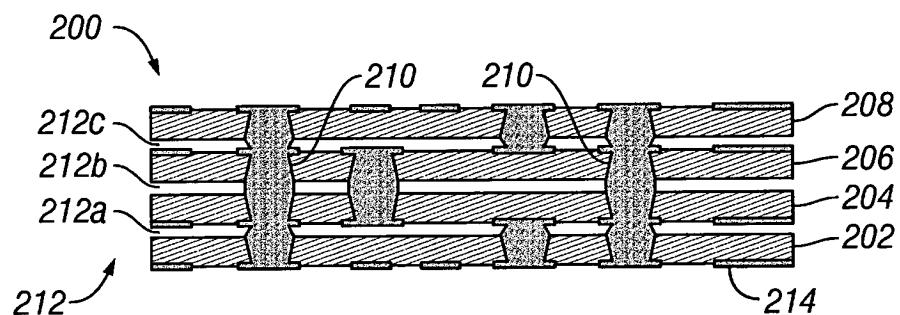


FIG. 53



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FIG. 54

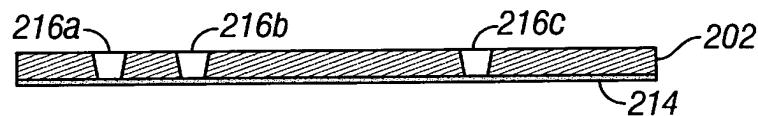


FIG. 55

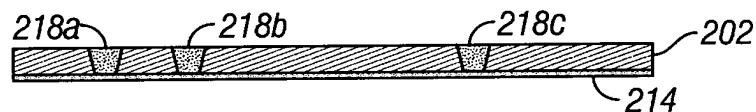


FIG. 56

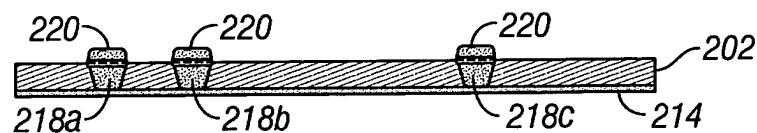


FIG. 57A



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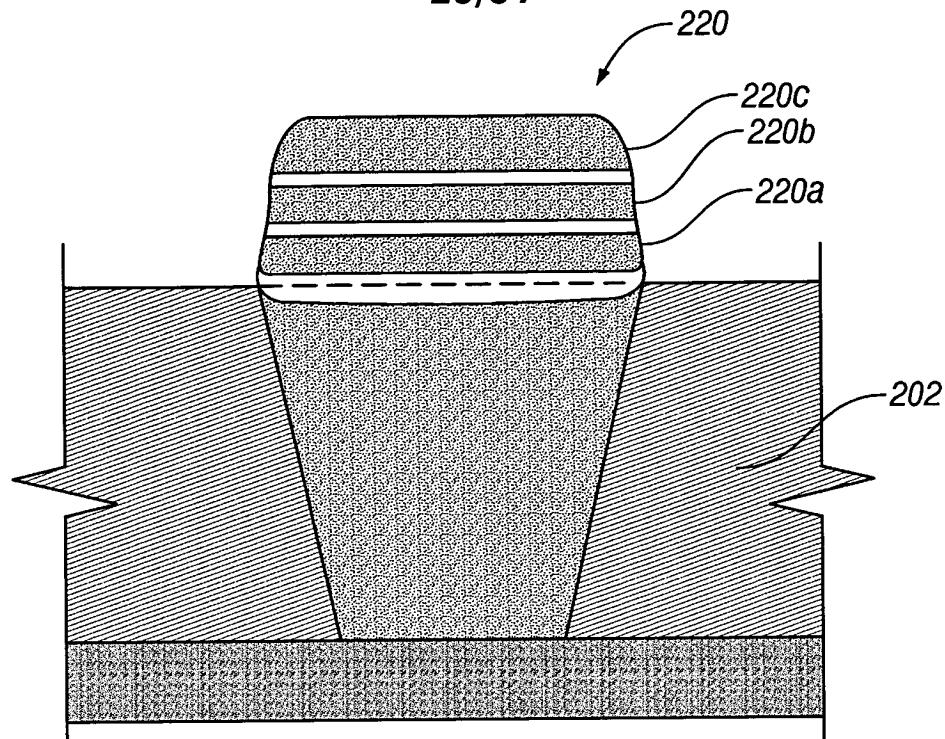


FIG. 57B

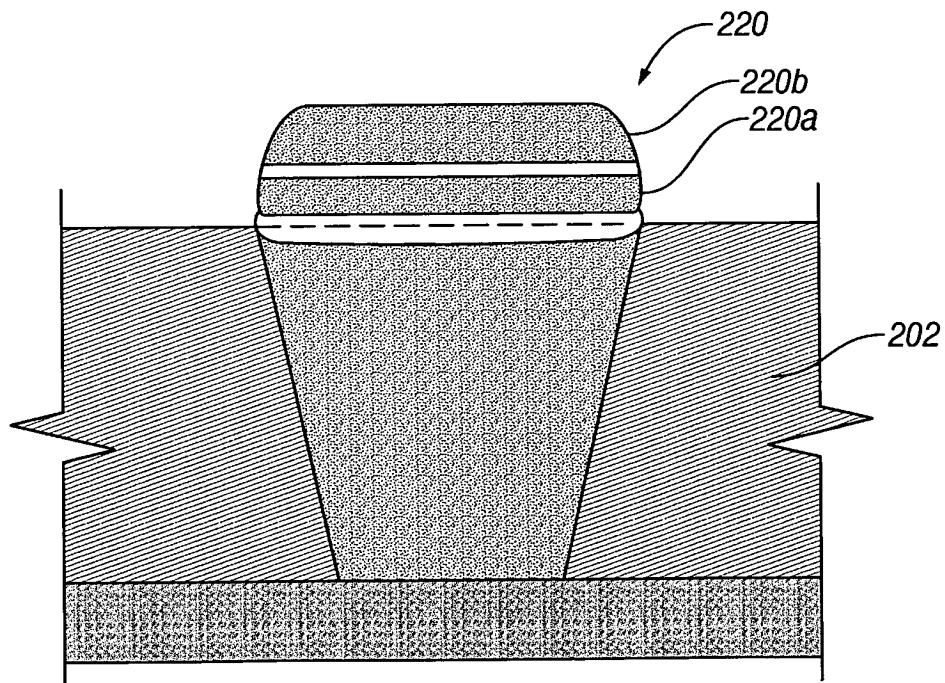


FIG. 57C



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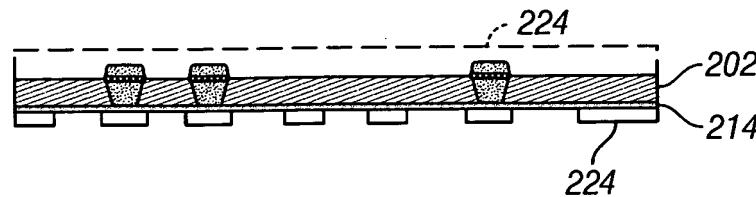


FIG. 58A

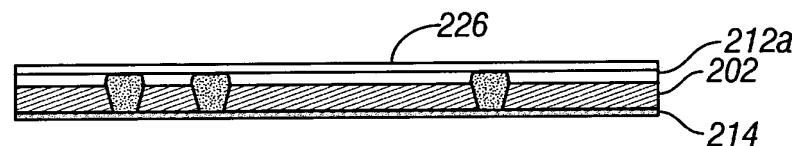


FIG. 58B



FIG. 59A

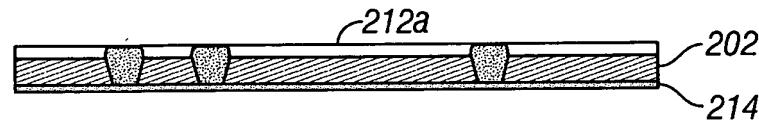


FIG. 59B



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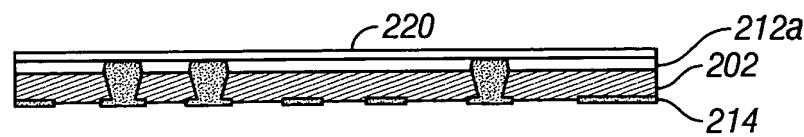


FIG. 60A

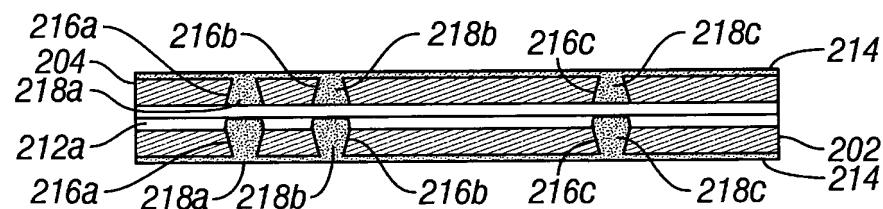


FIG. 60B

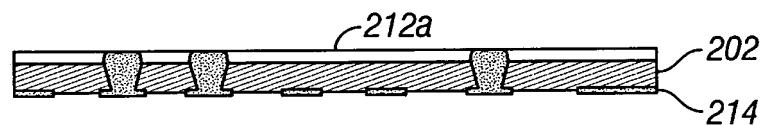


FIG. 61A

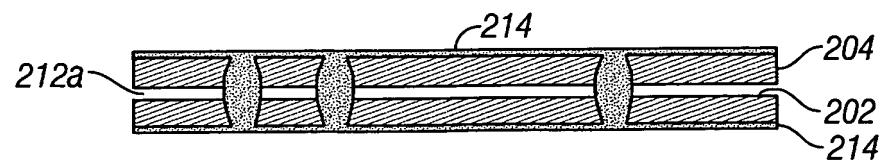


FIG. 61B



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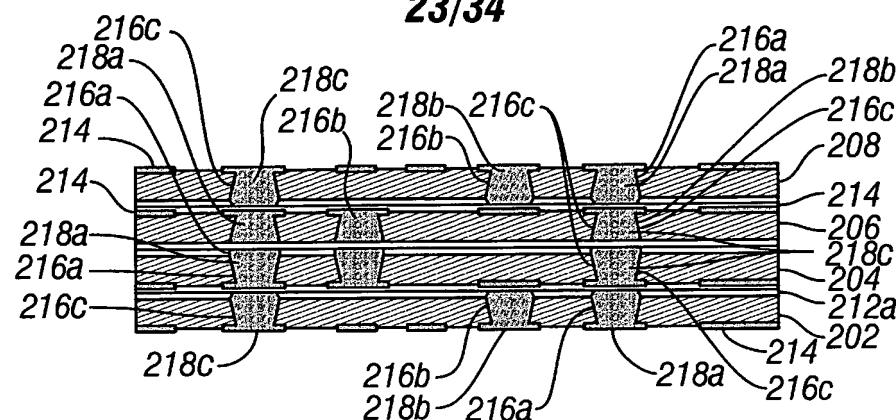


FIG.62A

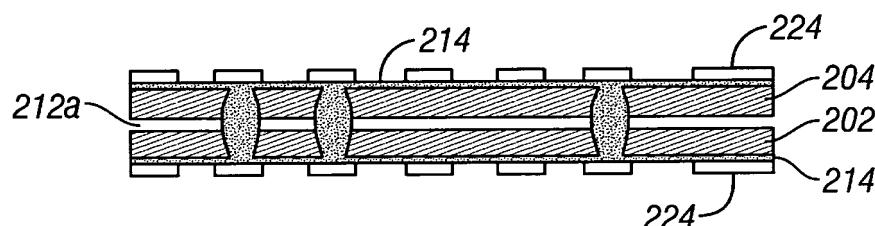


FIG.62B

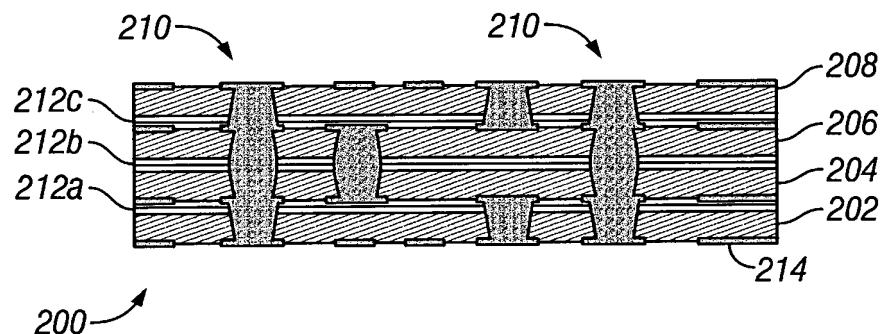


FIG.63A

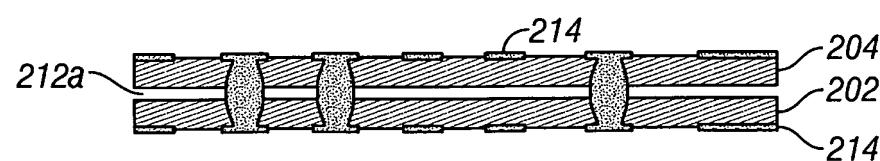


FIG.63B

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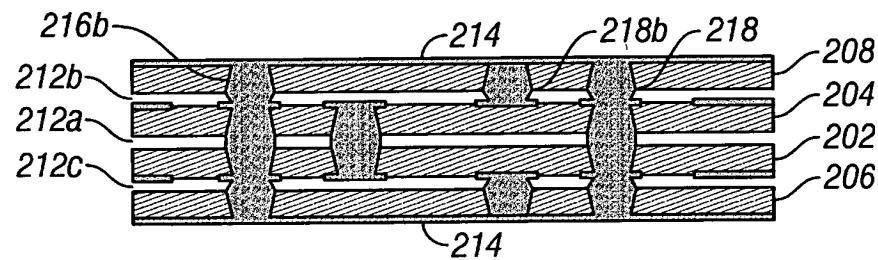


FIG.64B

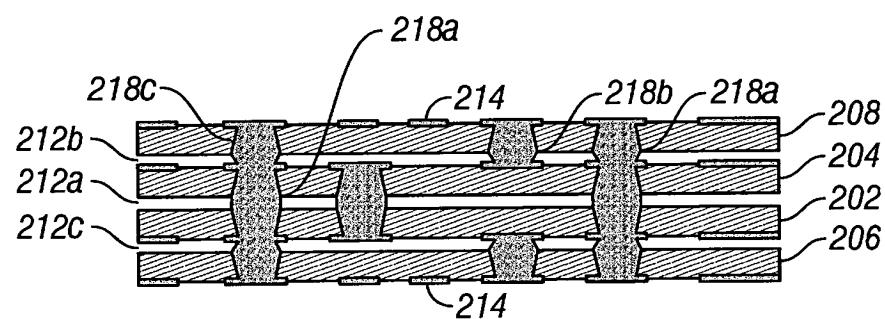


FIG.65B



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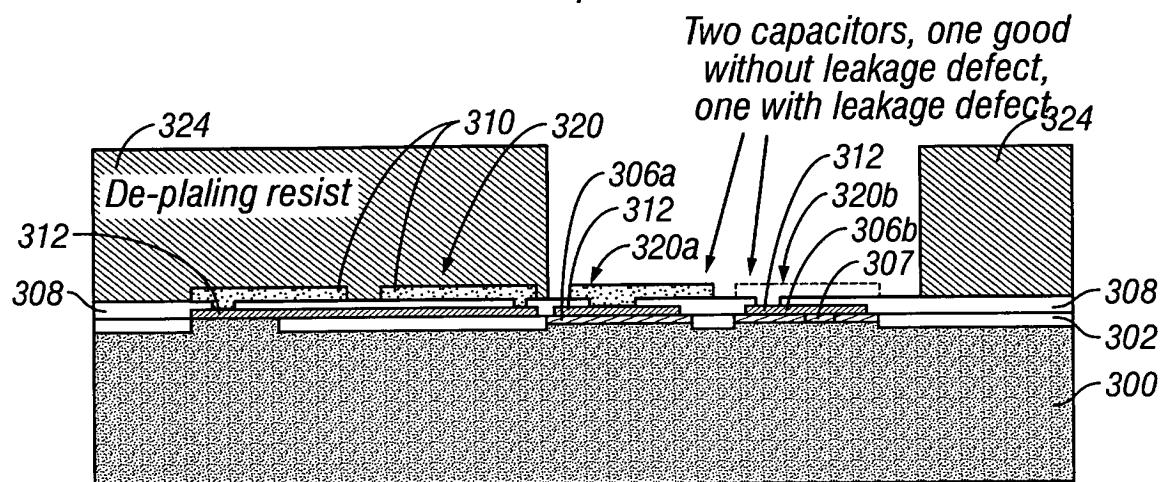


FIG. 66

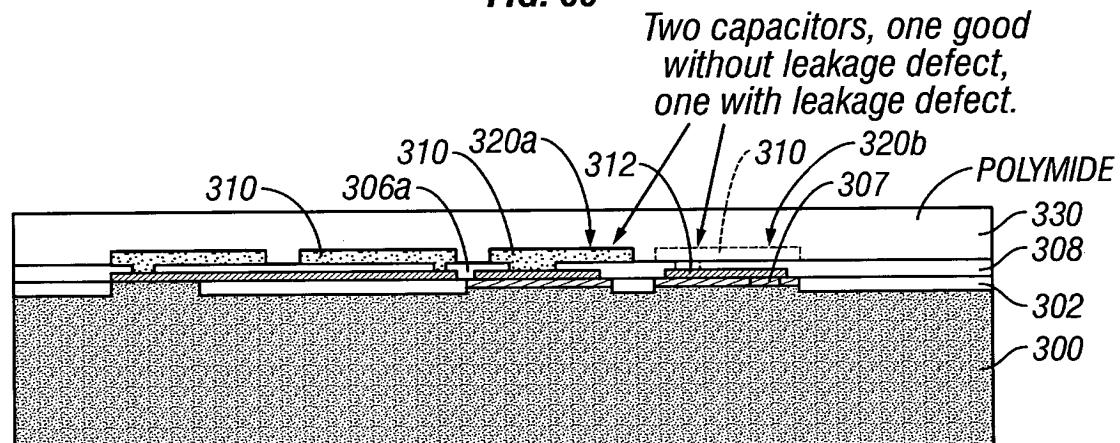


FIG. 67

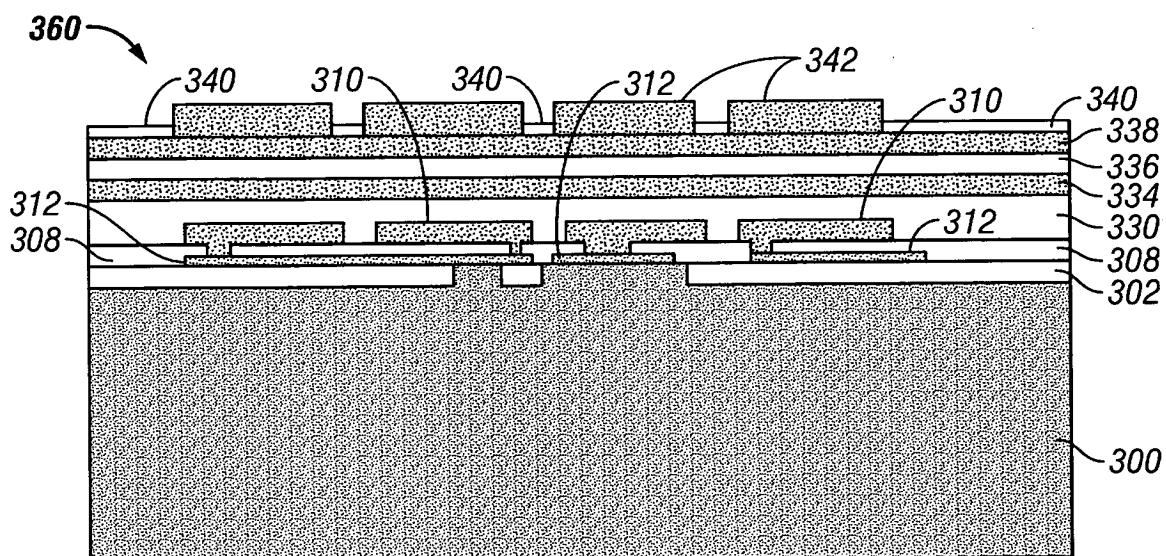


FIG. 68



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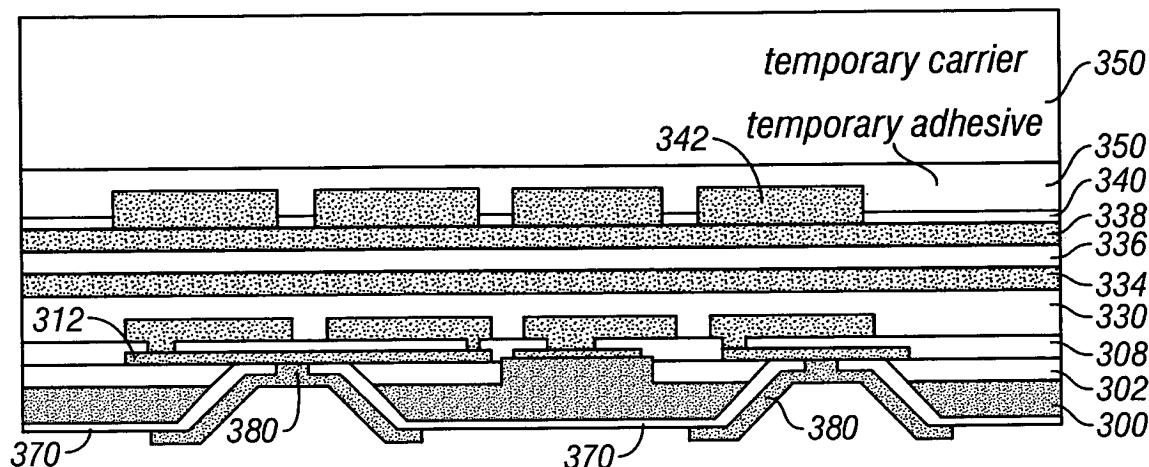


FIG. 69

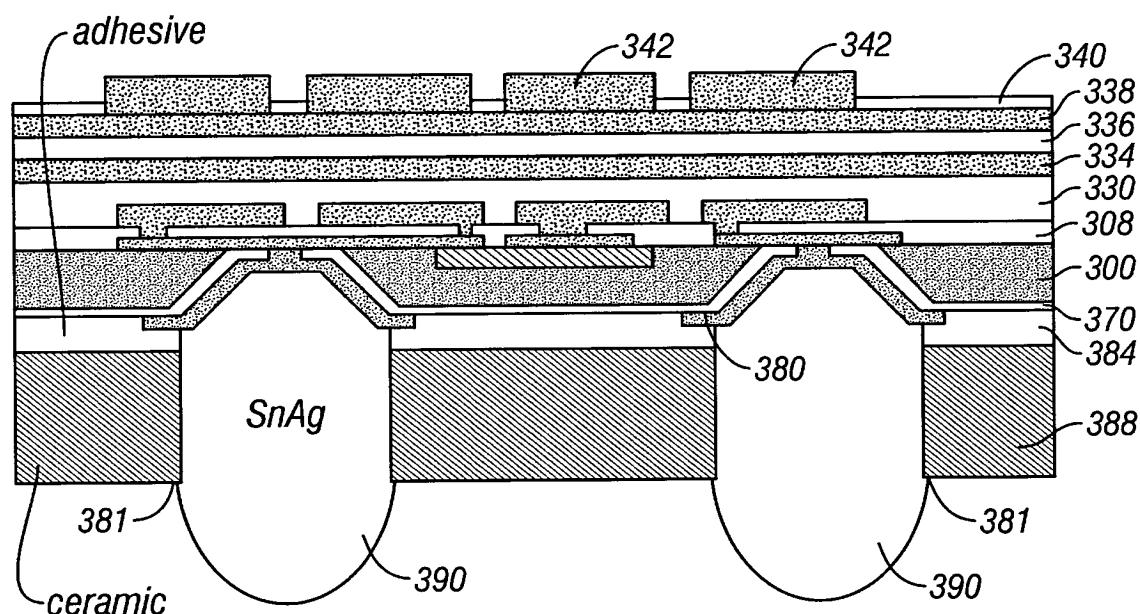


FIG. 70



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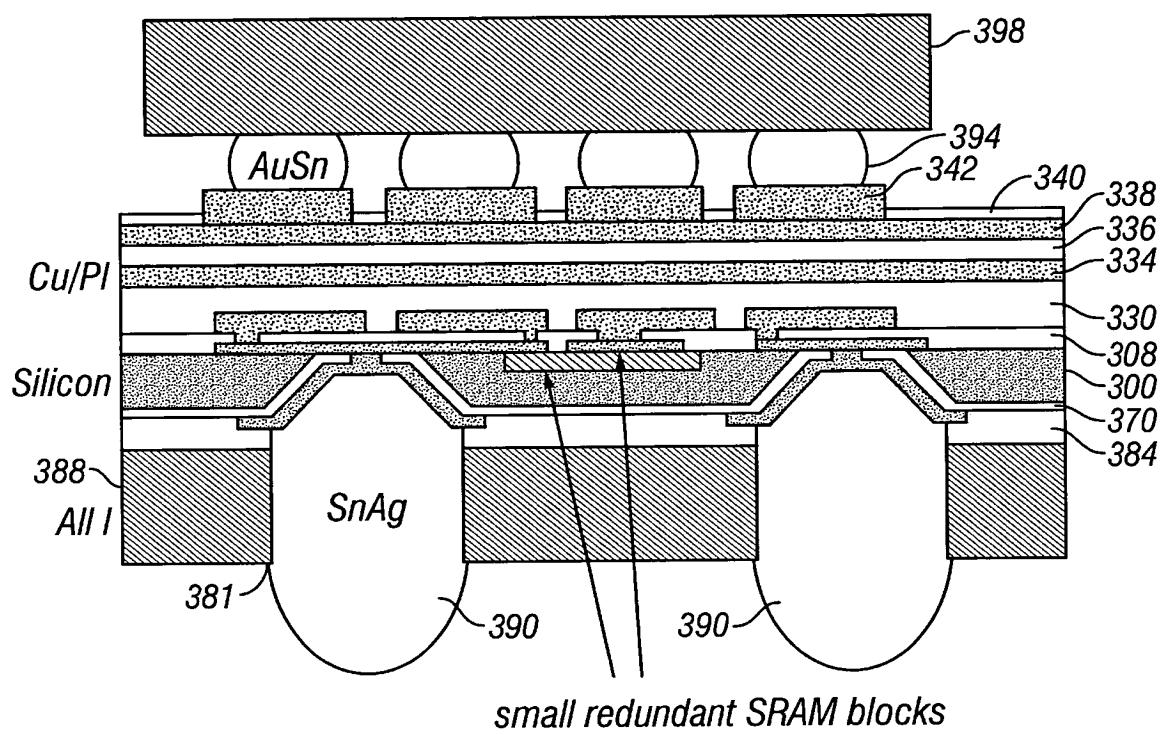


FIG. 71



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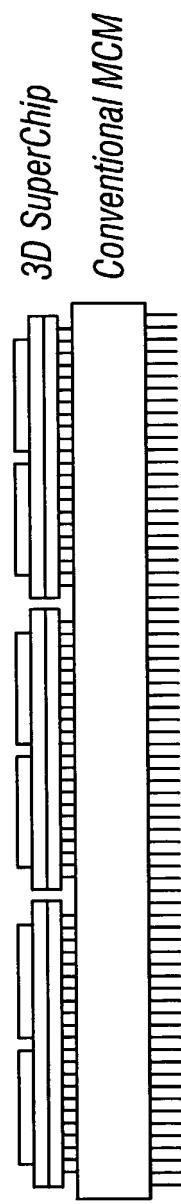


FIG. 72

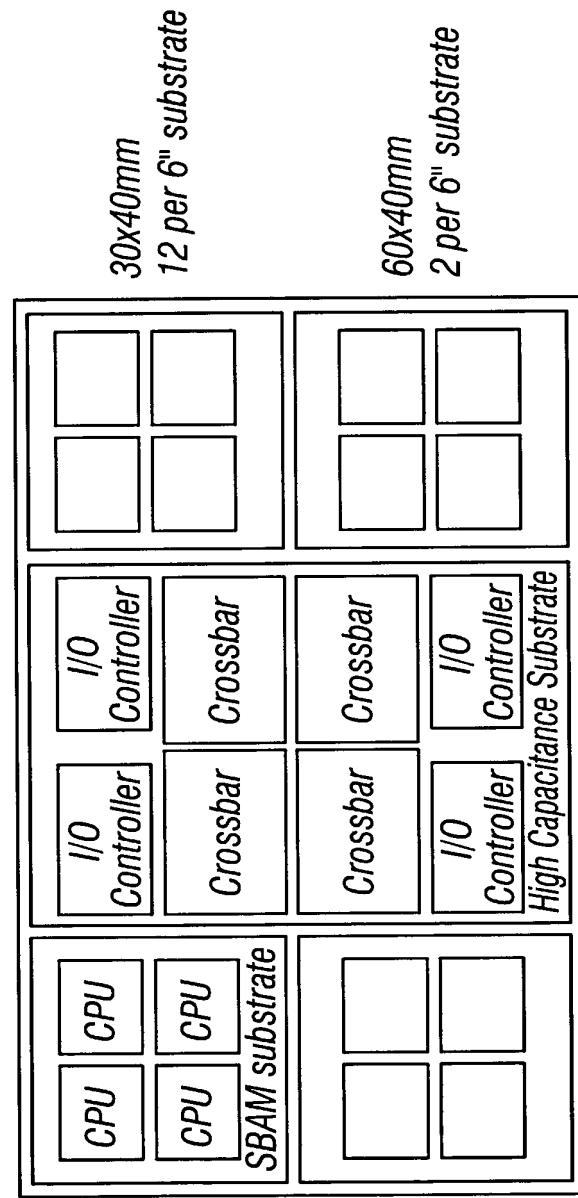


FIG. 73



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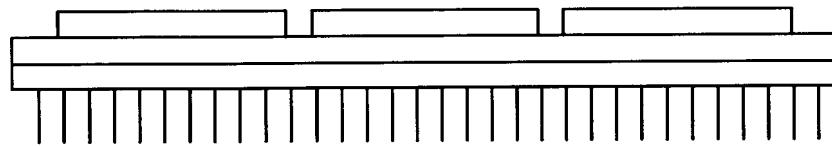


FIG. 74

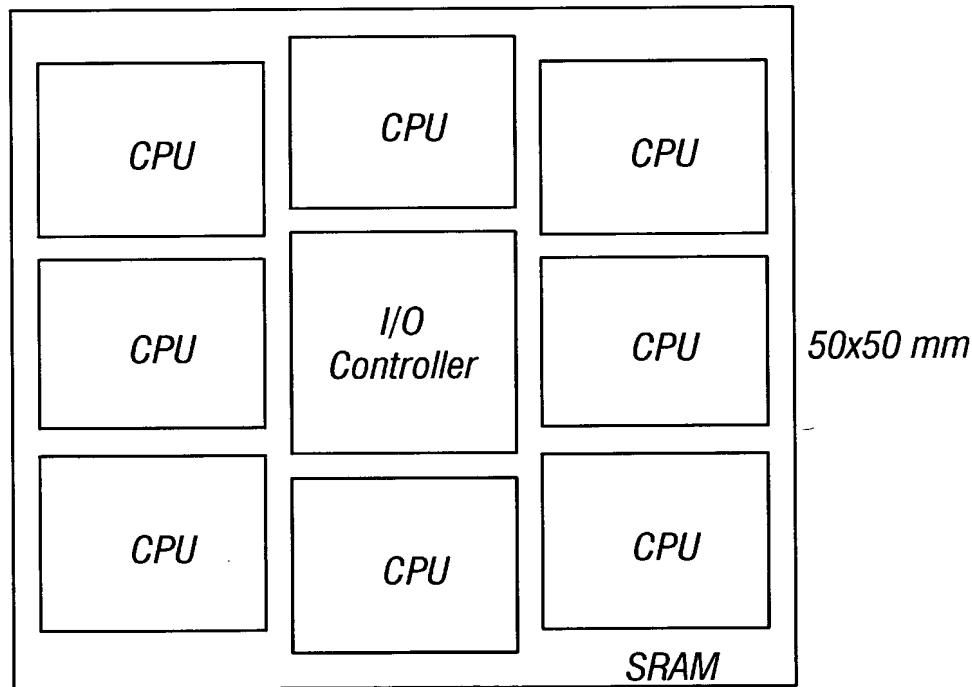


FIG. 75



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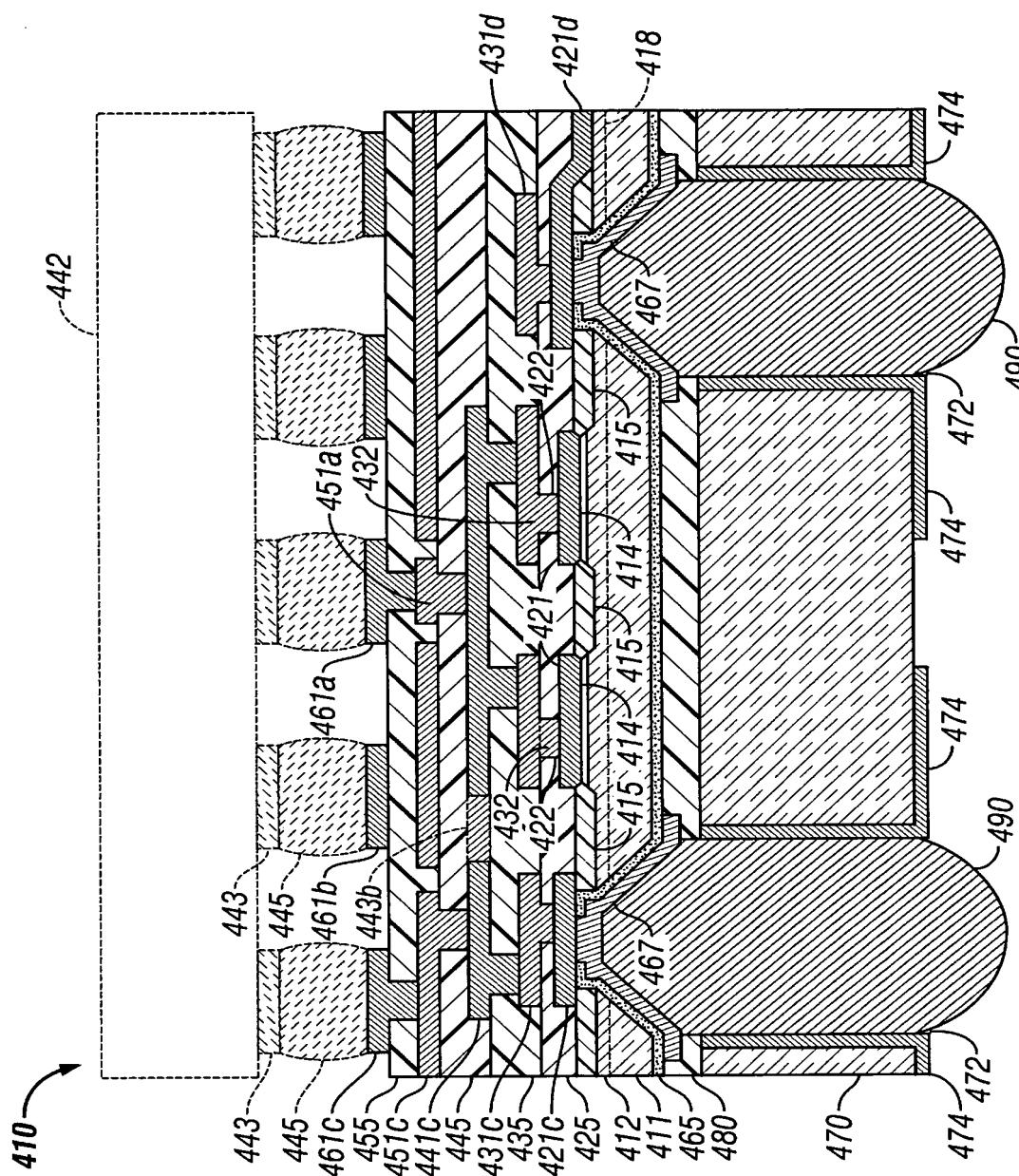


FIG. 76



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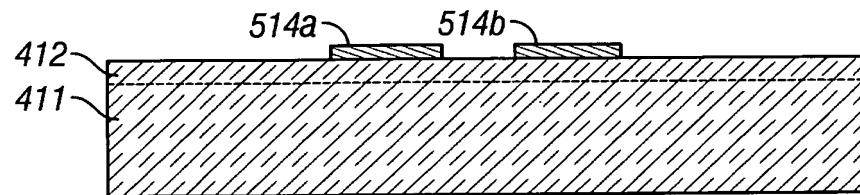


FIG. 77

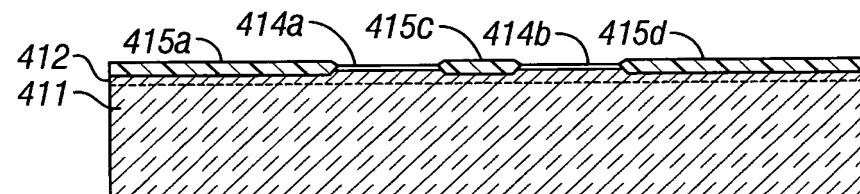


FIG. 78

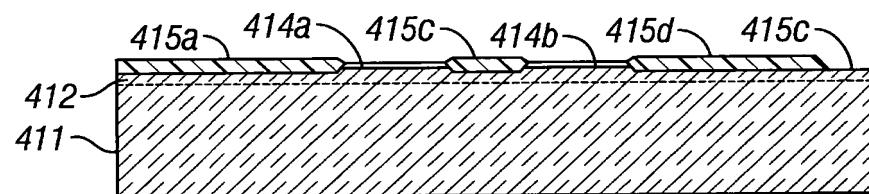


FIG. 79

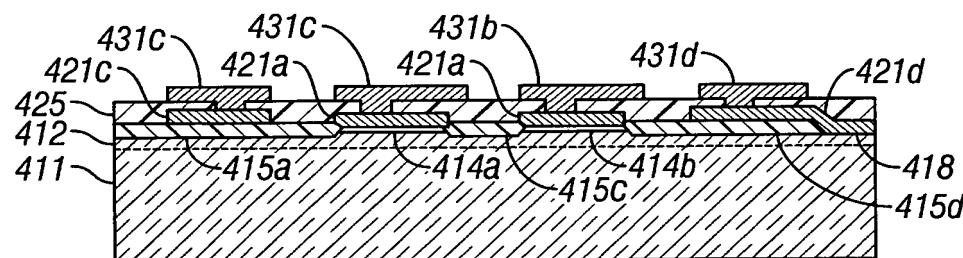


FIG. 80



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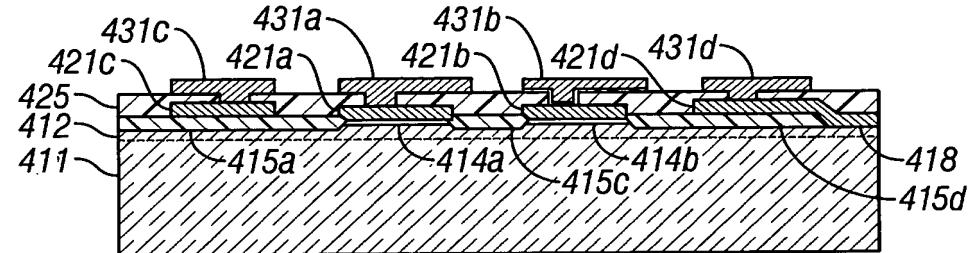


FIG. 81

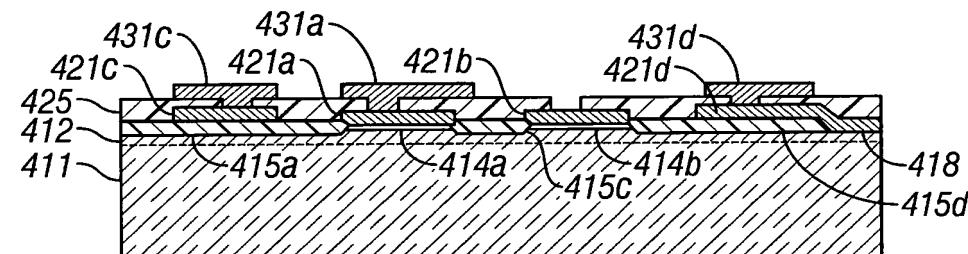


FIG. 82

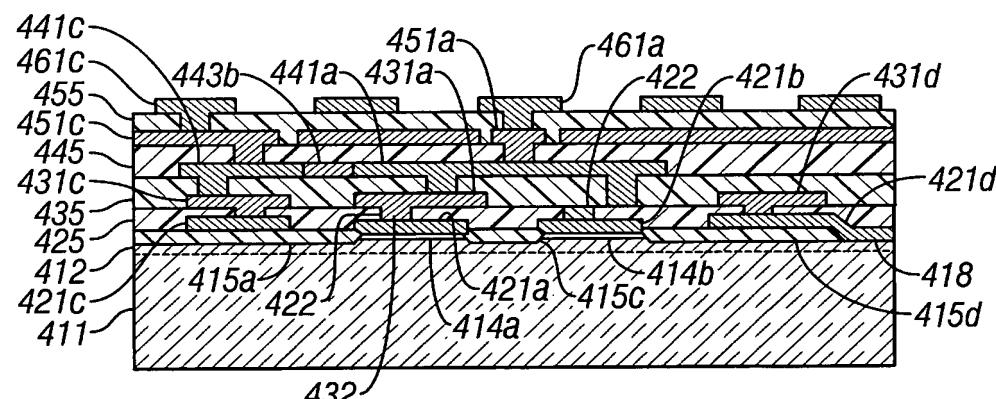


FIG. 83



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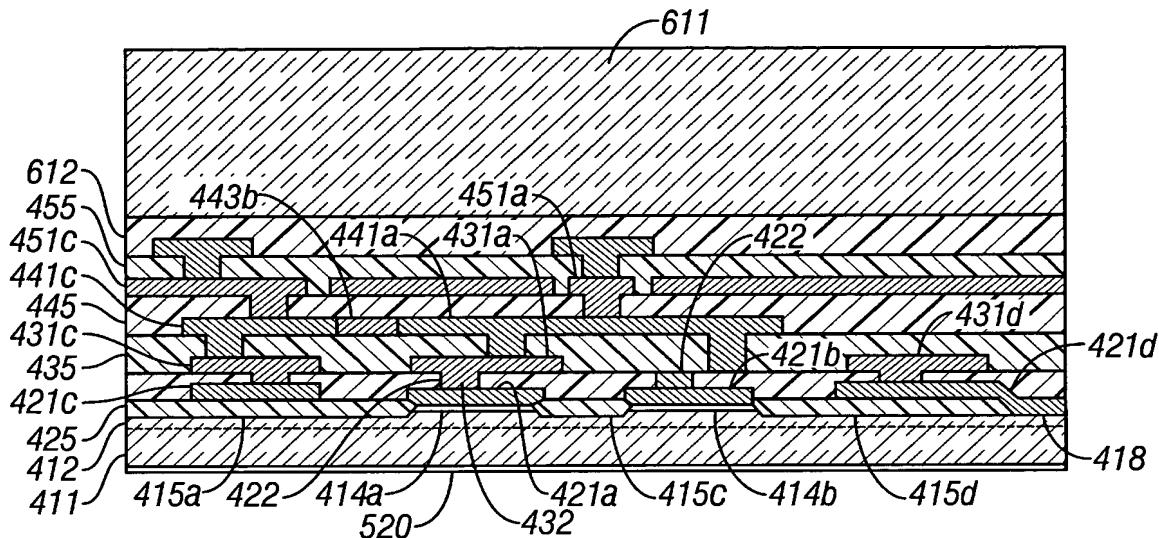


FIG. 84

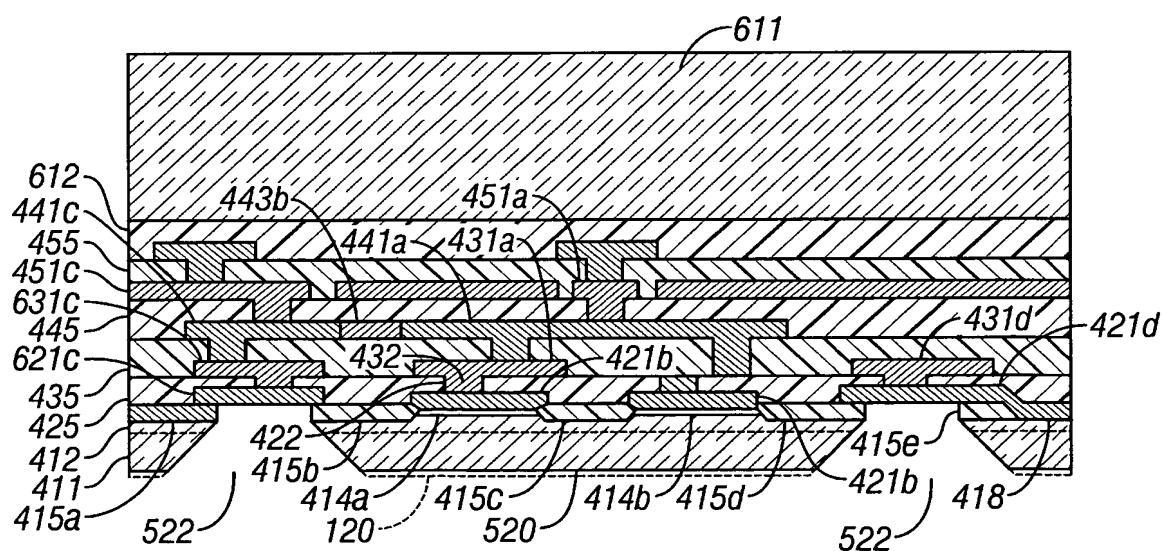


FIG. 85



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